

*B¹
C₁*

a protruding portion which is formed on the top face of the substrate and the top of
which serves as a dummy element for controlling a chemical mechanical polishing process; and
*S₂
S₃
C₂*
a conductive layer which is formed on the substrate so as to have a spiral shape and
which serves as an induction element,
wherein said protruding portion is formed to avoid being positioned in a region
directly below said conductive layer.

*B²
S₃
C₄*

10. (Twice Amended) A semiconductor device as set forth in claim 5, wherein said
protruding portion is formed to avoid being positioned in a region directly below said
conductive layer.

REMARKS

Favorable reconsideration, in light of the present amendments and following discussion, is respectfully requested. Claims 1-20 are pending; Claims 15-20 have been withdrawn from consideration; and Claims 1 and 10 have been amended. Applicant respectfully submits that no new matter has been added by this amendment.

In the outstanding Office Action, Claims 5-14 were rejected under 35 U.S.C. § 112, first paragraph; Claims 1 and 2 were rejected under 35 U.S.C. § 102(b) as anticipated by Applicant's Admitted Prior Art (AAPA); Claims 3 and 4 were rejected under 35 U.S.C. § 103(a) as unpatentable over AAPA in view of Wen et al. (U.S. Pat. No. 5,918,121, hereafter "the '121 patent"); Claims 5-7 and 10-12 were rejected under 35 U.S.C. § 103(a) as unpatentable over AAPA in view of Song (U.S. Pat. No. 6,075,257, hereafter "the '257 patent"); and Claims 8, 9, 13, and 14 were rejected under 35 U.S.C. § 103(a) as unpatentable over AAPA in view of and further in view of the '121 patent.